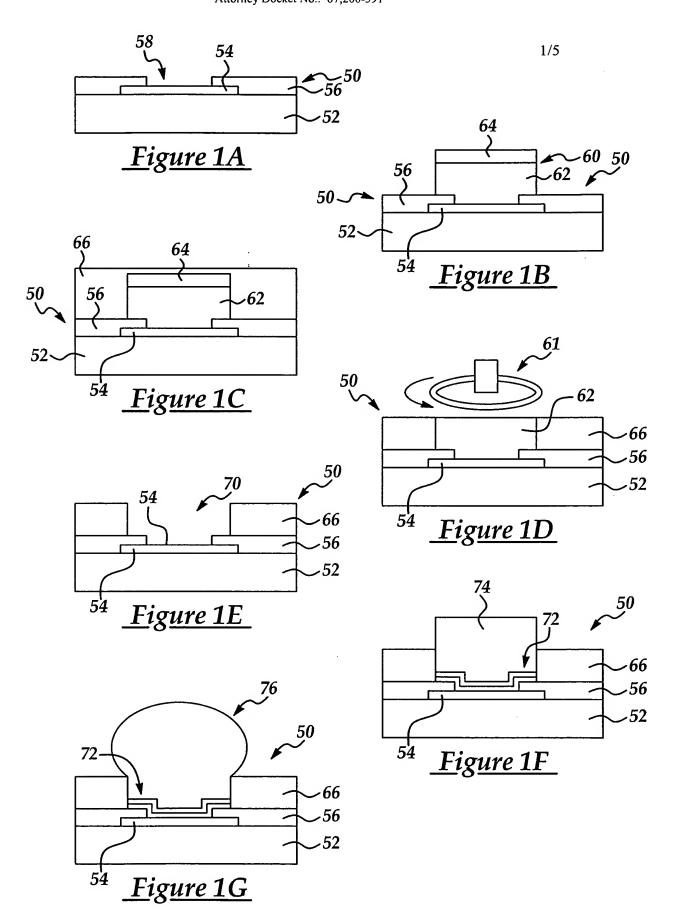
Inventor(s): Lee Serial No.: To Be Assigned Filed: Herewith

For:

Method of Making a Wafer Level Chip Scale Package Attorney Docket No.: 67,200-591



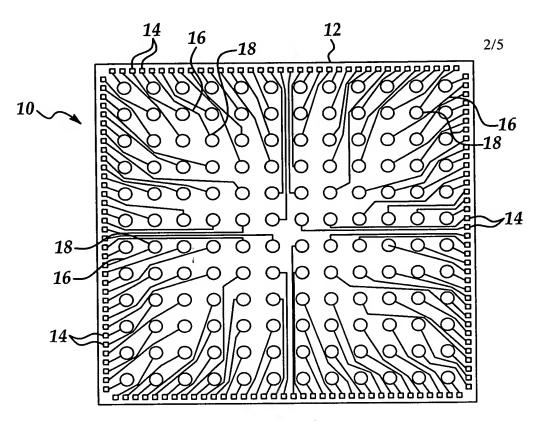
Inventor(s): Lee Serial No.: To Be Assigned Filed: Herewith

For:

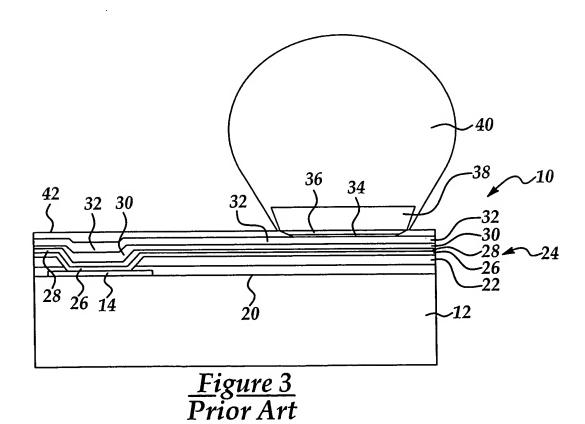
Filed: Herewith

Method of Making a Wafer Level Chip Scale Package

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<u>Figure 2</u> Prior Art

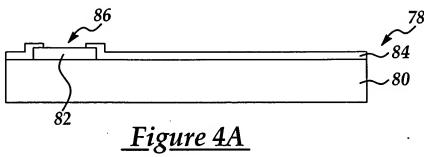


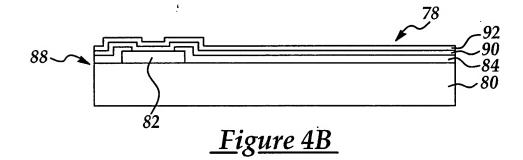
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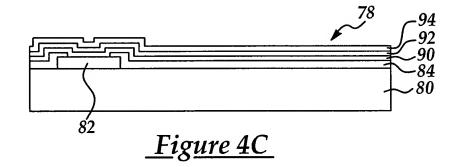
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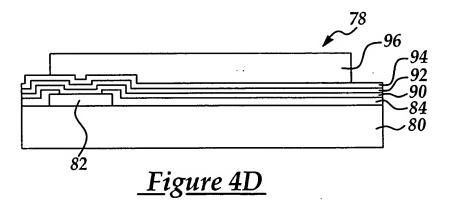
Method of Making a Wafer Level Chip Scale Package
Attorney Docket No.: 67,200-591

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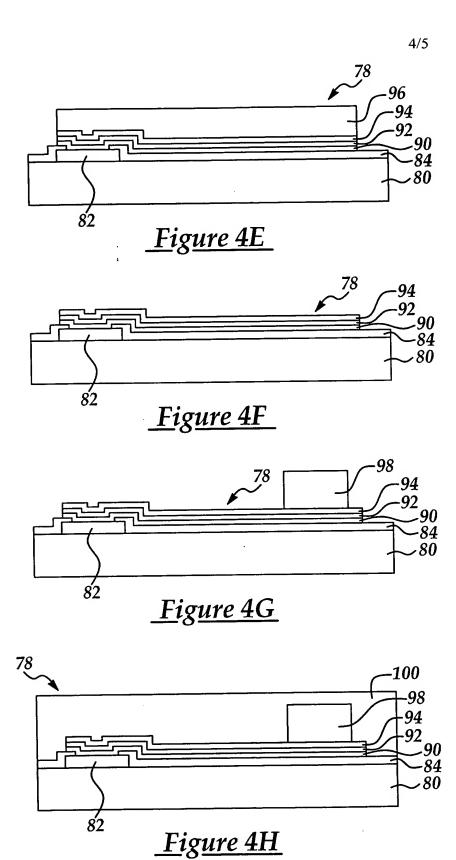




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